





### **Antiox AHM**

**OBSOLETE** 

#### **Description**

**ANTIOX AHM** is a synergistic blend of various antioxidant systems, including primary phenolic stabilizers, thio-esters for the long term stability and phosphites for high temperature protection. Its physical form ensures very low dust formation in handling and good flowing properties. The physical form of the components is primarily (but not completely) dusty in order to facilitate the dissolution / melting of the product.

#### **Application**

This formula has been designed to grant a wide spectrum protection either to hot-melt polymer systems or to polymer solutions. It can be used with adhesives, pressure sensitive adhesives, coatings and injection moulding or extrusion polymers.

# **Technical Specifications**

Method of analysis	MU	Standard
1. Total Solids	%	99±1
5. Melting Range	°C	110 - 140

# Handling

- For HOT-MELT adhesives, ANTIOX AHM is very efficient at the following concentrations:
  - thermoplastic rubbers, like SIS, SBS:
    1.2-1.5% on rubber content;
  - ethylene-vinylacetate (EVA, type ELVAX, etc.): 0.3-0.4% on EVA content;

- thermoplastic polyurethane (e.g. ESTANE, DESMOCOLL, etc.): 0.2-0.4% on PU content
- polyamides (e.g. reammide, Versamid, etc.): 0.5-1.0% on PA content
- For SOLVENT BASED Adhesives, ANTIOX AHM is very efficient at the following concentrations:
  - natural rubber, SBR, chloroprene rubber, polyisoprene, butyl rubber: 0.25-0.5% on dry content.

**ANTIOX AHM** can be added directly to the compound, together with the other ingredients, or it can be predispersed into one of them, or dissolved in case of solvent based products.

When used in a hot-melt continuos system (extrusion process), we recommend adding a liquid component (such as a liquid rosin ester, naphtenic oil, or similar), to give some tack to the surface of granules. This allows for an equal distribution of the antioxidant over the total mass (volumetric dosing).

### **Storing**

**ANTIOX AHM** must be stored in a dry place to avoid agglomeration.

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